

N-Channel Enhancement Mode Power MOSFET

Description

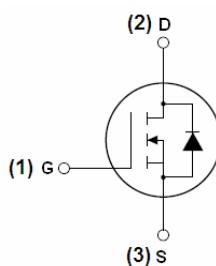
The HM50N06D uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. It can be used in a wide variety of applications.

General Features

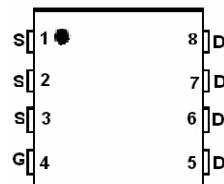
- $V_{DS} = 60V, I_D = 50A$
- $R_{DS(ON)} < 6.5m\Omega @ V_{GS}=10V$ (Typ:5mΩ)
- High density cell design for ultra low $R_{DS(on)}$
- Fully characterized avalanche voltage and current
- Low gate to drain charge to reduce switching losses

Application

- Power switching application
- Load switch



Schematic diagram



Marking and pin assignment

Package Marking and Ordering Information

| Device Marking | Device | Device Package | Reel Size | Tape width | Quantity |
|----------------|----------|----------------|-----------|------------|----------|
| HM50N06D | HM50N06D | DFN5X6-8L | - | - | - |

Absolute Maximum Ratings ($T_C=25^\circ C$ unless otherwise noted)

| Parameter | Symbol | Limit | Unit |
|--|---------------------|------------|------|
| Drain-Source Voltage | V_{DS} | 60 | V |
| Gate-Source Voltage | V_{GS} | ± 20 | V |
| Drain Current-Continuous | I_D | 50 | A |
| Drain Current-Continuous($T_C=100^\circ C$) | $I_D (100^\circ C)$ | 35 | A |
| Pulsed Drain Current | I_{DM} | 200 | A |
| Maximum Power Dissipation | P_D | 60 | W |
| Operating Junction and Storage Temperature Range | T_J, T_{STG} | -55 To 150 | °C |

Thermal Characteristic

| | | | |
|--|-----------------|----|------|
| Thermal Resistance,Junction-to-Ambient ^(Note 2) | $R_{\theta JA}$ | 40 | °C/W |
|--|-----------------|----|------|

Electrical Characteristics (TC=25°C unless otherwise noted)

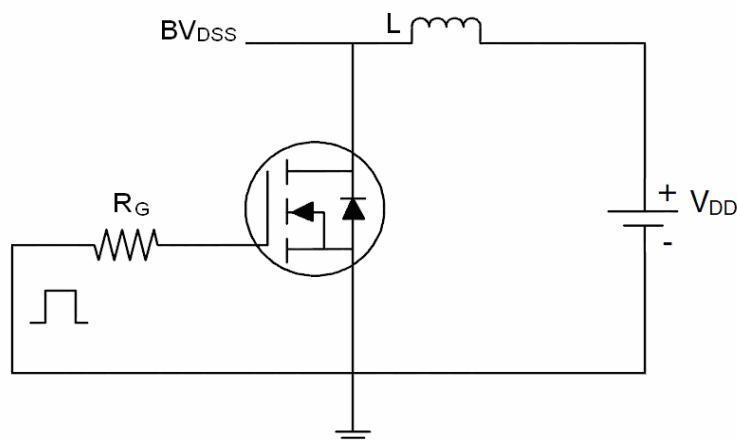
| Parameter | Symbol | Condition | Min | Typ | Max | Unit |
|--|--------------|---|-----|------|-----------|-----------|
| Off Characteristics | | | | | | |
| Drain-Source Breakdown Voltage | V_{DSS} | $V_{GS}=0V, I_D=250\mu A$ | 60 | | - | V |
| Zero Gate Voltage Drain Current | I_{DSS} | $V_{DS}=60V, V_{GS}=0V$ | - | - | 1 | μA |
| Gate-Body Leakage Current | I_{GSS} | $V_{GS}=\pm 20V, V_{DS}=0V$ | - | - | ± 100 | nA |
| On Characteristics ^(Note 3) | | | | | | |
| Gate Threshold Voltage | $V_{GS(th)}$ | $V_{DS}=V_{GS}, I_D=250\mu A$ | 2 | 3 | 4 | V |
| Drain-Source On-State Resistance | $R_{DS(ON)}$ | $V_{GS}=10V, I_D=50A$ | - | 5 | 6.5 | $m\Omega$ |
| Forward Transconductance | g_{FS} | $V_{DS}=5V, I_D=50A$ | 20 | - | - | S |
| Dynamic Characteristics ^(Note 4) | | | | | | |
| Input Capacitance | C_{iss} | $V_{DS}=30V, V_{GS}=0V, F=1.0MHz$ | - | 2800 | - | PF |
| Output Capacitance | C_{oss} | | - | 430 | - | PF |
| Reverse Transfer Capacitance | C_{rss} | | - | 190 | - | PF |
| Switching Characteristics ^(Note 4) | | | | | | |
| Turn-on Delay Time | $t_{d(on)}$ | $V_{DD}=30V, R_L=1\Omega$ $V_{GS}=10V, R_{GEN}=3\Omega$ | - | 8 | - | nS |
| Turn-on Rise Time | t_r | | - | 6 | - | nS |
| Turn-Off Delay Time | $t_{d(off)}$ | | - | 30 | - | nS |
| Turn-Off Fall Time | t_f | | - | 5 | - | nS |
| Total Gate Charge | Q_g | $V_{DS}=30V, I_D=50A, V_{GS}=10V$ | - | 45 | - | nC |
| Gate-Source Charge | Q_{gs} | | - | 10 | - | nC |
| Gate-Drain Charge | Q_{gd} | | - | 15 | - | nC |
| Drain-Source Diode Characteristics | | | | | | |
| Diode Forward Voltage ^(Note 3) | V_{SD} | $V_{GS}=0V, I_S=50A$ | - | - | 1.2 | V |
| Diode Forward Current ^(Note 2) | I_S | - | - | - | 50 | A |
| Reverse Recovery Time | t_{rr} | $T_J = 25^{\circ}C, IF = 50A$ $di/dt = 100A/\mu s$ ^(Note 3) | - | 41 | - | nS |
| Reverse Recovery Charge | Q_{rr} | | - | 51 | - | nC |
| Forward Turn-On Time | t_{on} | Intrinsic turn-on time is negligible (turn-on is dominated by LS+LD) | | | | |

Notes:

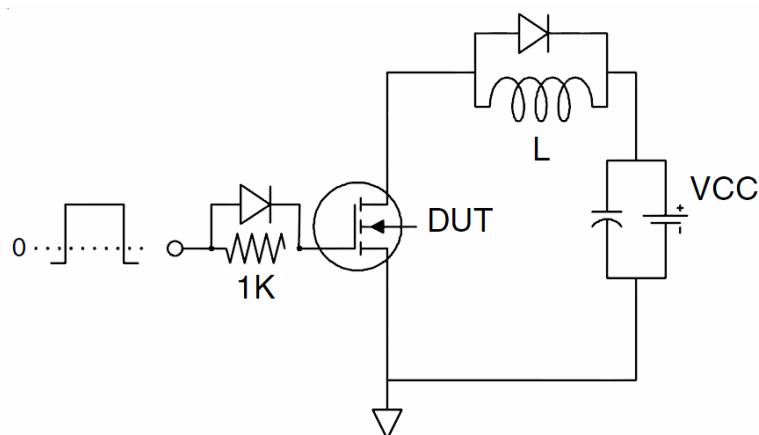
1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, $t \leq 10$ sec.
3. Pulse Test: Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 2\%$.
4. Guaranteed by design, not subject to production

Test Circuit

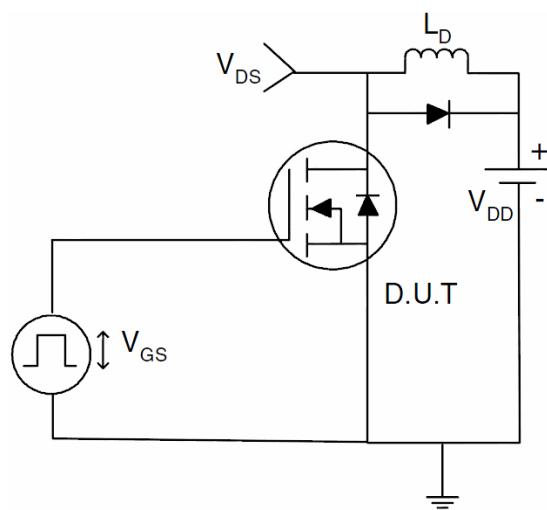
1) E_{AS} test Circuit



2) Gate charge test Circuit



3) Switch Time Test Circuit



Typical Electrical and Thermal Characteristics (Curves)

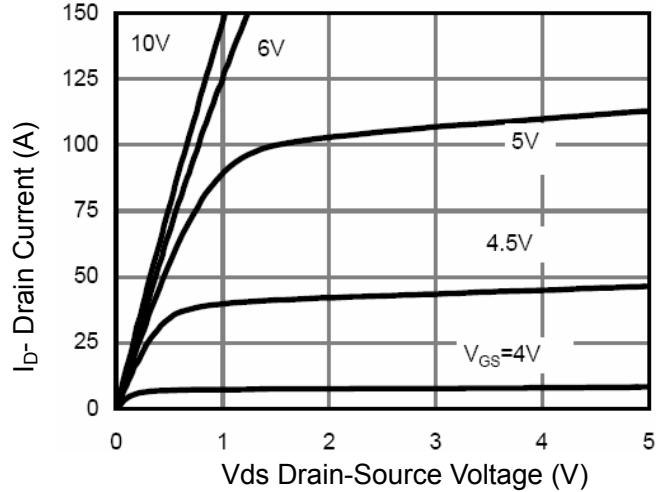


Figure 1 Output Characteristics

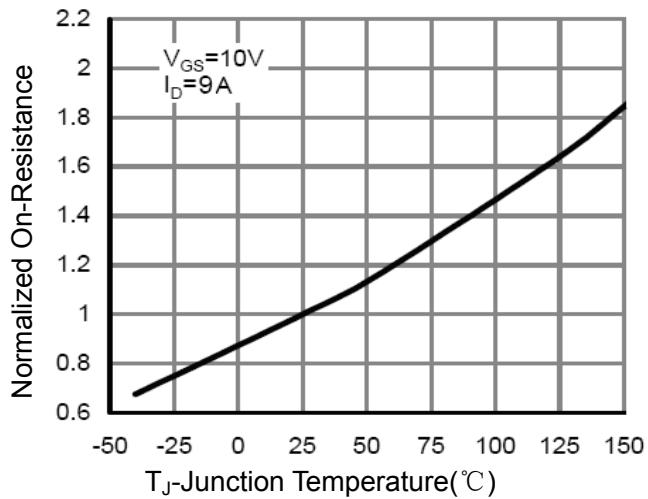


Figure 4 Rdson-JunctionTemperature

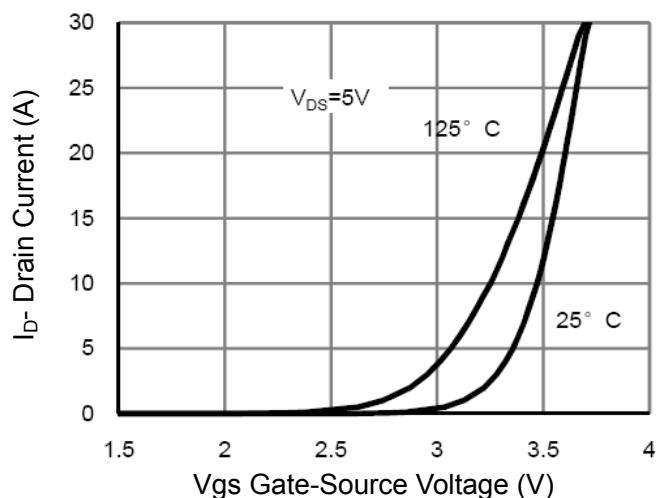


Figure 2 Transfer Characteristics

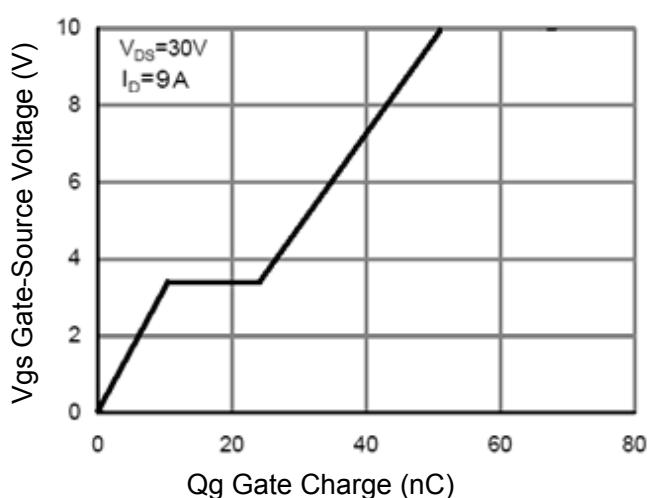


Figure 5 Gate Charge

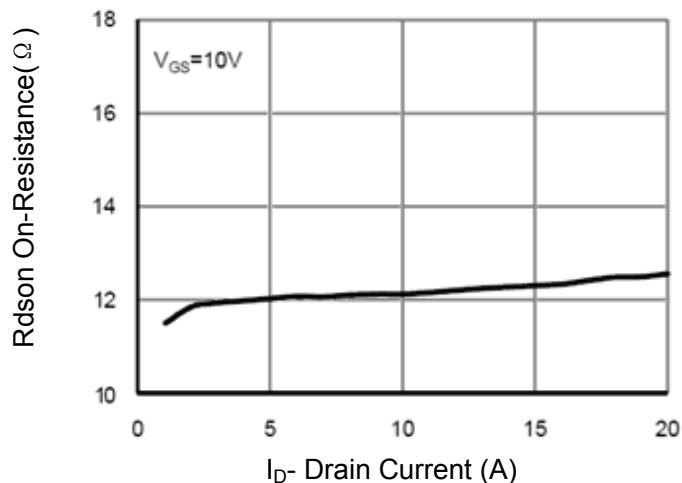


Figure 3 Rdson- Drain Current

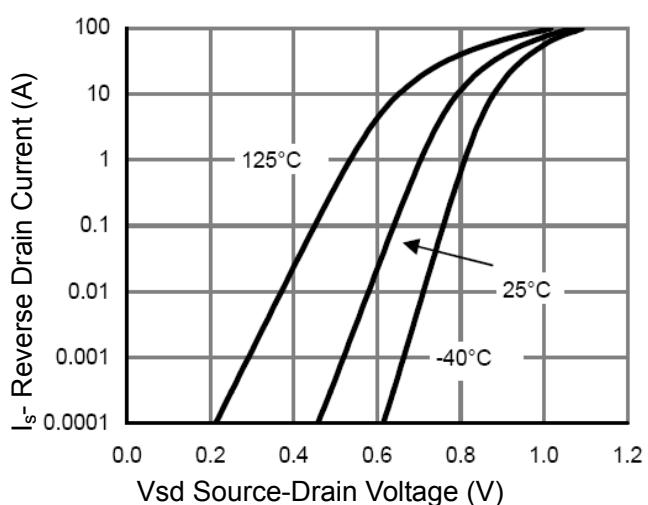


Figure 6 Source- Drain Diode Forward

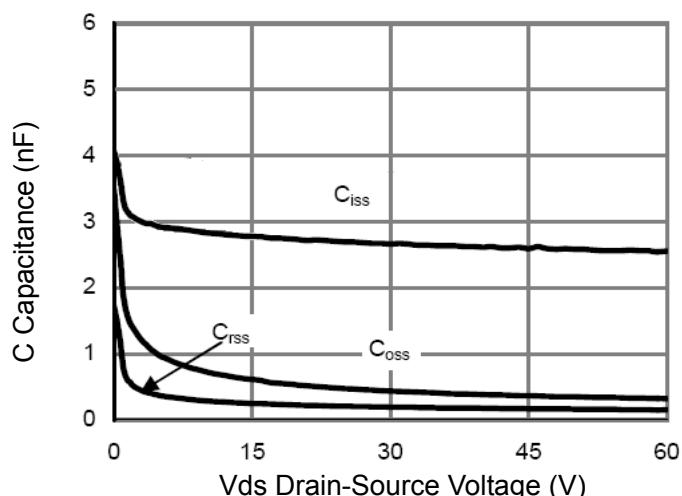


Figure 7 Capacitance vs Vds

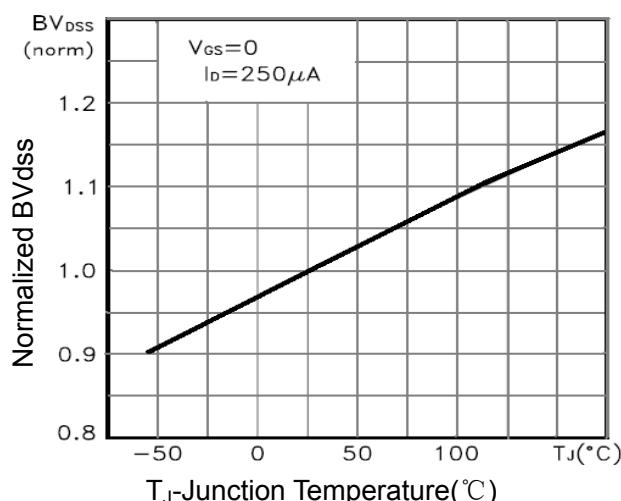


Figure 9 BV_{dss} vs Junction Temperature

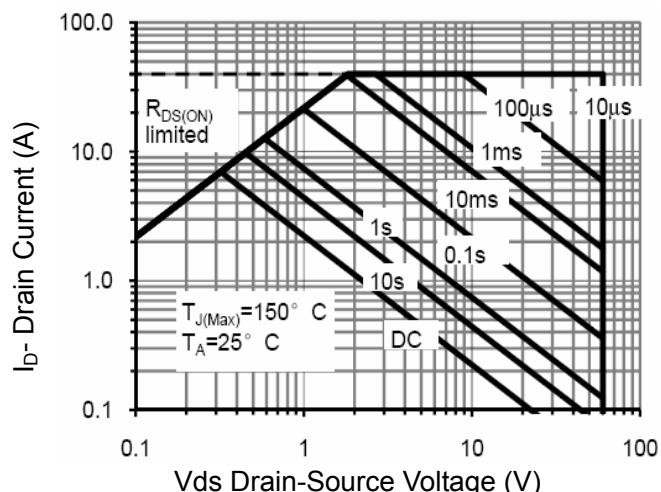


Figure 8 Safe Operation Area

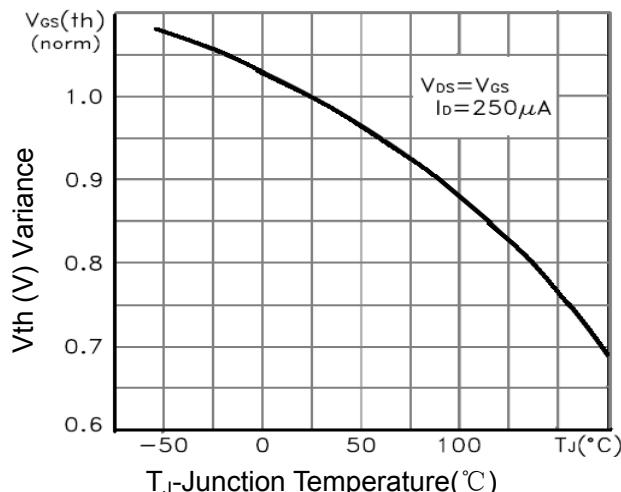


Figure 10 $V_{GS(th)}$ vs Junction Temperature

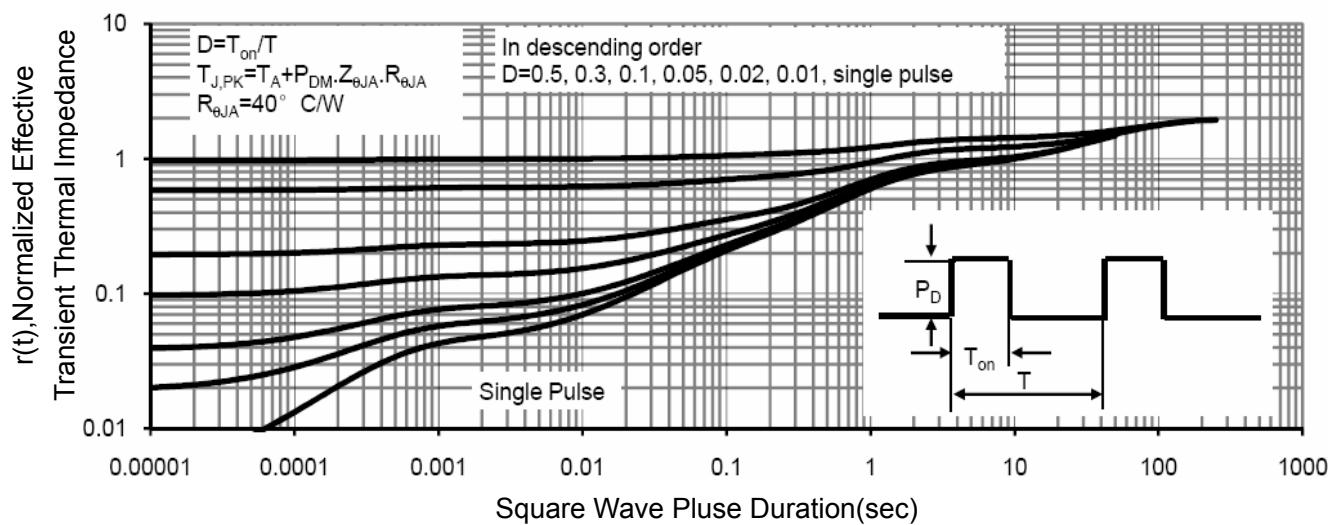
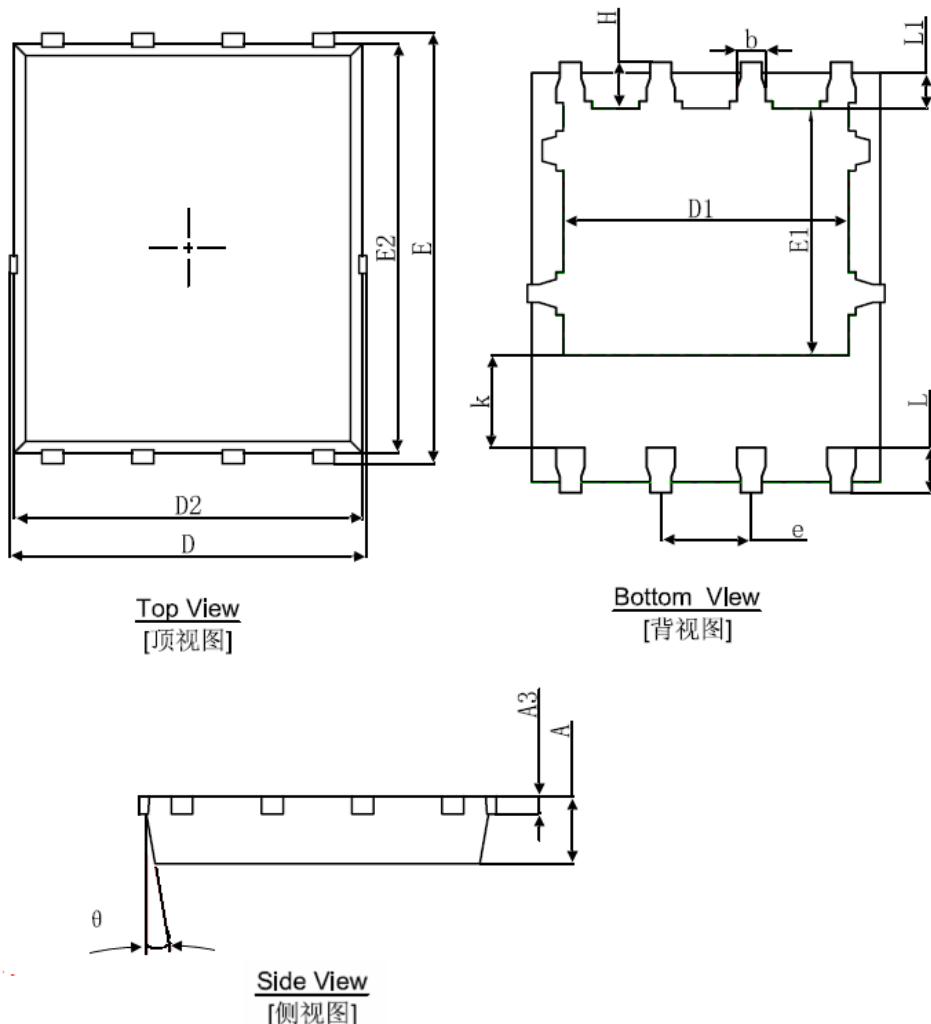


Figure 11 Normalized Maximum Transient Thermal Impedance

DFN5X6-8L Package Information



| Symbol | Dimensions In Millimeters | | Dimensions In Inches | |
|--------|---------------------------|-------|----------------------|-------|
| | Min. | Max. | Min. | Max. |
| A | 0.900 | 1.000 | 0.035 | 0.039 |
| A3 | 0.254REF. | | 0.010REF. | |
| D | 4.944 | 5.096 | 0.195 | 0.201 |
| E | 5.974 | 6.126 | 0.235 | 0.241 |
| D1 | 3.910 | 4.110 | 0.154 | 0.162 |
| E1 | 3.375 | 3.575 | 0.133 | 0.141 |
| D2 | 4.824 | 4.976 | 0.190 | 0.196 |
| E2 | 5.674 | 5.826 | 0.223 | 0.229 |
| k | 1.190 | 1.390 | 0.047 | 0.055 |
| b | 0.350 | 0.450 | 0.014 | 0.018 |
| e | 1.270TYP. | | 0.050TYP. | |
| L | 0.559 | 0.711 | 0.022 | 0.028 |
| L1 | 0.424 | 0.576 | 0.017 | 0.023 |
| H | 0.574 | 0.726 | 0.023 | 0.029 |
| θ | 8° | | 8° | |
| | 12° | | 12° | |